

Adapters

QFP112 TET

Target CPU package: QFP112
 Body size: 20 mm x 20 mm
 Pitch: 0.65 mm
 POD target layout: T_QFP144

Can be used with:

- MC9S12XDP512 Active PRO POD
- MC9S12XDP512 Active GT POD

This adapter is used when MC9S12XDP512 Active PRO/GT POD emulates MC9S12XAx, MC9S12XBx, MC9S12XDx or MC9S12XDGx devices in the QFP112 package.

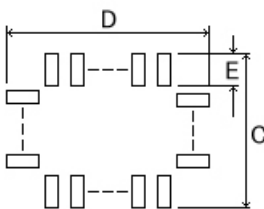
Described adapter parts can be used only with listed PODs. Disregarding this note may result in a hardware failure of the emulation system and the target.

► Available Adapter Parts (by ordering code):

- **IA112TQ-SOLDER**

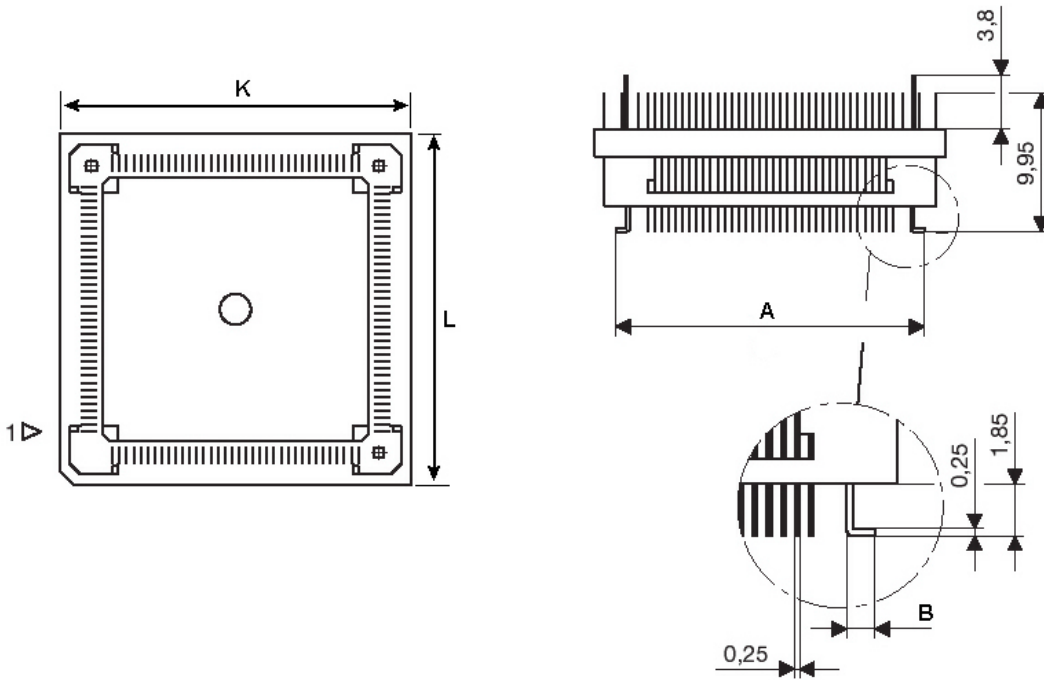


Solder part, which is being soldered to the target.



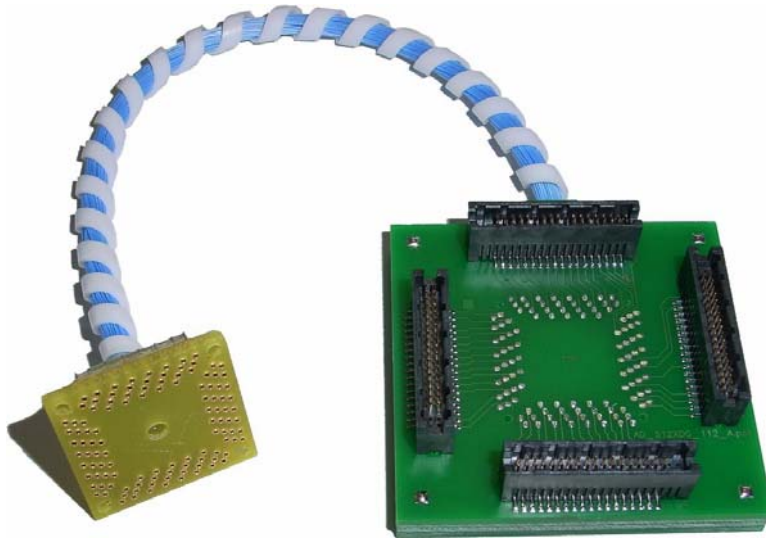
(Unit: mm)						
A	B	C	D	E	K	L
22	1.000	23.0	23.0	1.9	25.3	25.3

Recommended (by TET) PCB footprint size



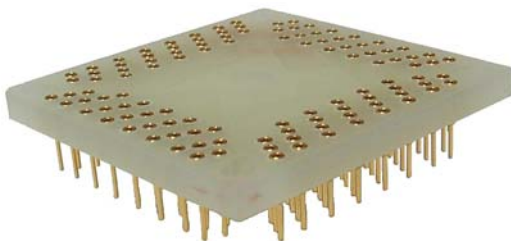
IA112TQ-SOLDER dimensions

- **IA144P112TQ-W-XDG128**



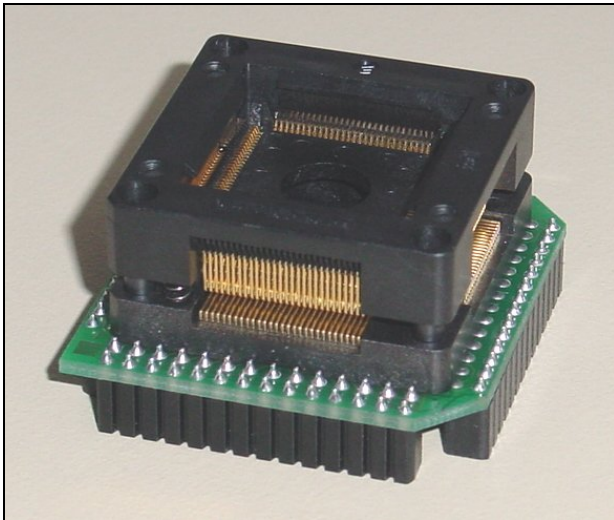
The IA144P112TQ-W-XDG128 represents flexible connection between the POD and the target.

- **IA112TQEXT**



The IA112TQEXT is a 3 mm extension. When it's used to prolong the IA112TQ-FIXED part, it may solve connection problems in a target with a restricted space around the CPU. It can be used also as a "socket saver" to protect the more expensive IA112TQ-SOLDER part which may be damaged due to the carelessness when connecting/disconnecting the POD from the IA112TQ-SOLDER part.

- IA112TQSOC

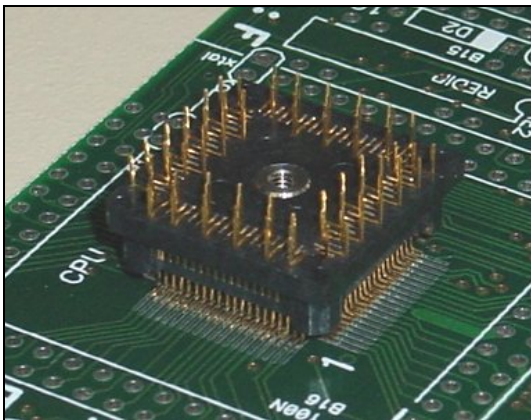


The IA112TQSOC is used to connect the CPU directly to the target.

► Assembly

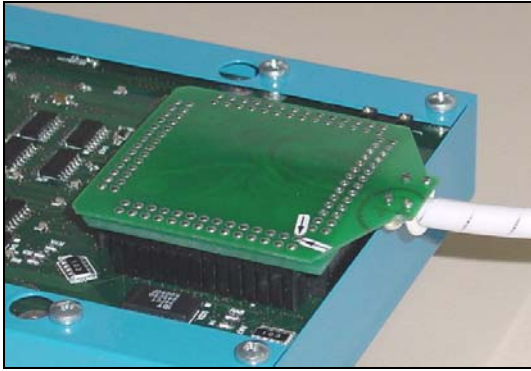
While assembling the adapter and connecting the POD to the target, pay attention to pin 1 to prevent any damages of the hardware, which may result from incorrect assembly.

Step 1: Solder the IA80TQ-SOLDER to the target PCB.

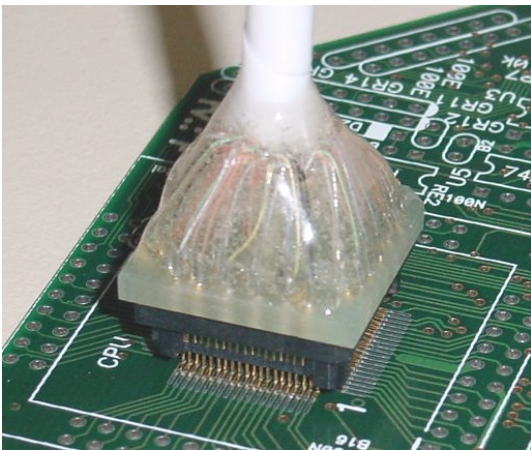


Now, if optionally the IA80TQEXT is used, it must be placed on top. It is not used in this particular case.

Step 2: Connect the IA112P80TQ-W-XDG128 to the POD.



Step 3: Finally, connect the POD to the target.



Precaution must be taken after the POD is connected to the target. Adapter parts may break due to the user carelessness.

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